

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph beginning at page 36, line 2, with the following rewritten paragraph:

-- ~~The A~~ film carrier tape for mounting electronic components ~~according to the present invention includes~~ comprises an insulating film and, on the surface thereof, an inner connection terminal, an outer connection terminal and a wiring for connecting these terminals, and further ~~comprises~~ includes a solder resist layer covered in such a way that the connection terminals are exposed, and the tape secures ~~electric~~ an electrical connection of a connection terminal of an electronic component and the inner connection terminal by applying an ultrasonic wave on the inner connection terminal in mounting the electronic component;

~~wherein~~. The wiring positioned from a part where the inner connection terminal is electrically connected with the connection terminal of the electronic component to the edge of the solder resist layer and wiring in a 1000  $\mu$ m length from the edge of the solder resist, which wiring is protected by the solder resist layer, are formed in an almost straight shape.

~~\_\_\_\_\_The film carrier tape for mounting electronic components having such a the above structure according to the present invention does not receive any concentration of stress in application with when an ultrasonic wave is applied and thereby cracks or disconnection are hardly caused~~ disconnections in the wiring pattern are virtually eliminated. --